

RF and Acoustic methods for Power & Communication

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Driving Applications: Supply Chain Hardware Integrity for Electronics Defense (SHIELD)

Radio frequency systems that can wirelessly charge and communicate to miniature and chip scale devices are important for the emerging application of hardware root-of-trust embeddable in packages of electronic components. This work develops two complimentary approaches. The first approach uses near field inductive wireless link, and the second approach is based on an acoustic link. Both approaches address the same challenges and enable long range communication in a small form factor.



fabricated on a thin Duroid board to validate the theory